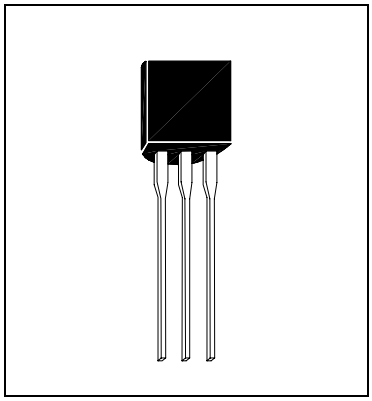
HBC556

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HBC556 is primarily intended for use in driver stage of audio amplifiers.

Features

- High Breakdown Voltage: 65V at IC=1mA
- High AC Current Gain: 75-500 at IC=2mA,VCE=5V,f=1MHz

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 500 mW
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -80 V
  VCEO Collector to Emitter Voltage ..... -65 V
  VEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -100 mA

Characteristics (Ta=25°C)

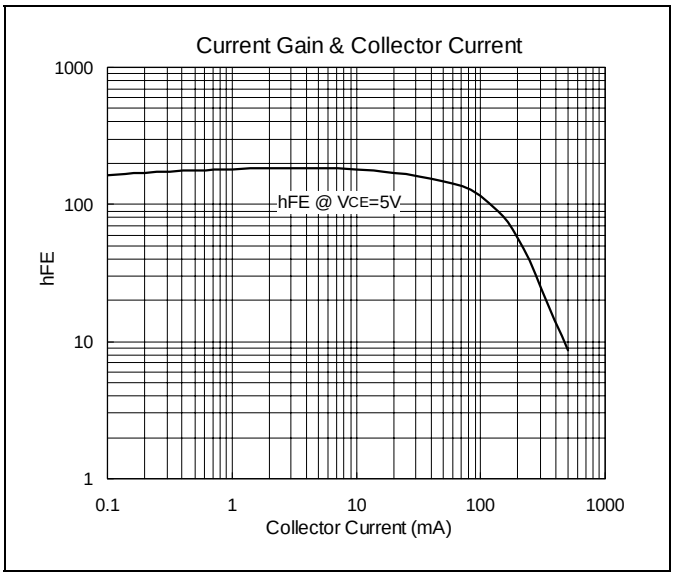
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-80	-	-	V	IC=-100uA, IE=0
BVCEO	-65	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-15	nA	VCB=-30V, IE=0
VBE(on)1	-600	-	-750	mV	IC=-2mA, VCE=-5V
VBE(on)2	-	-	-820	mV	IC=-10mA, VCE=-5V
*VCE(sat)1	-	-	-300	mV	IC=-10mA, IB=-0.5mA
*VCE(sat)2	-	-	-650	mV	IC=-100mA, IB=-5mA
*hFE	75	-	475		VCE=-5V, IC=-2mA,
fT	-	300	-	MHZ	VCE=-5V, IC=-10mA, f=100MHz
Cob	-	4.5	-	Pf	VCB=-10V, IE=0, f=1MHz

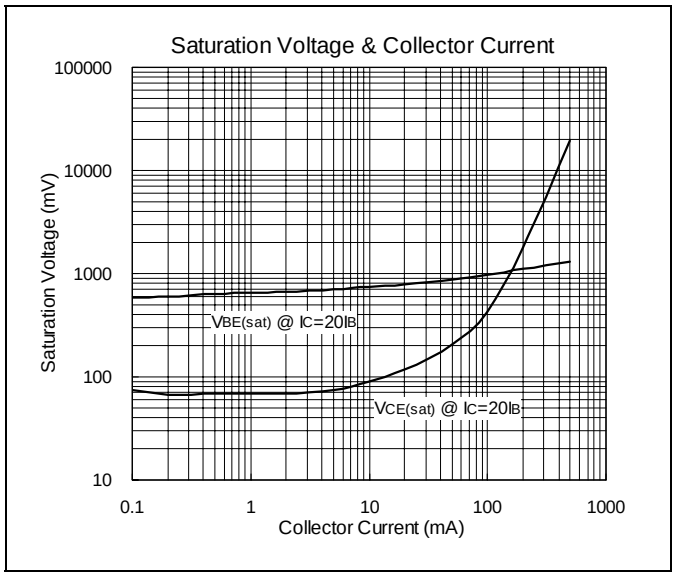
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

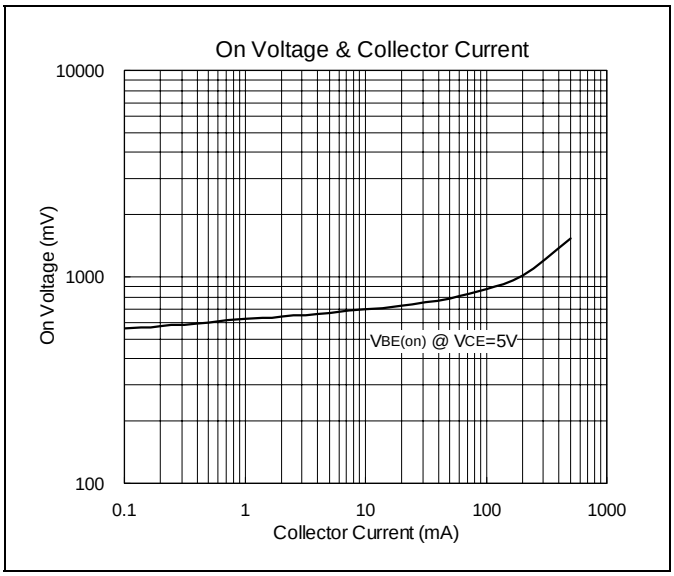
Classification of hFE

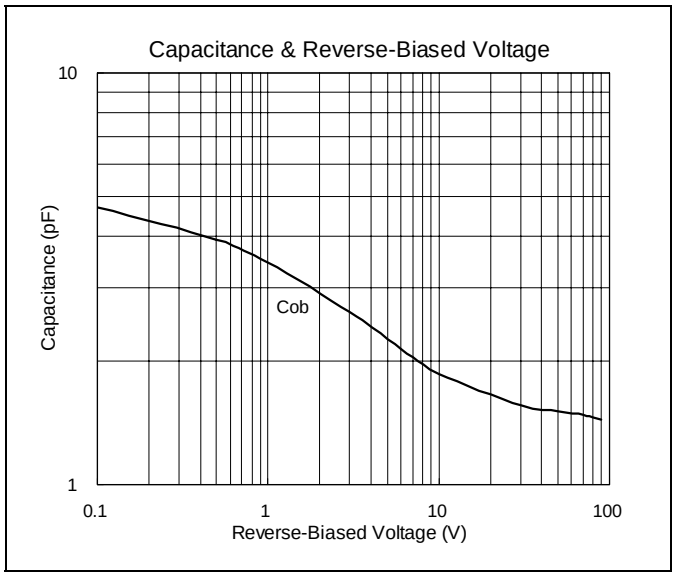
Rank	A	B	Normal
Range	125-250	220-475	75-475

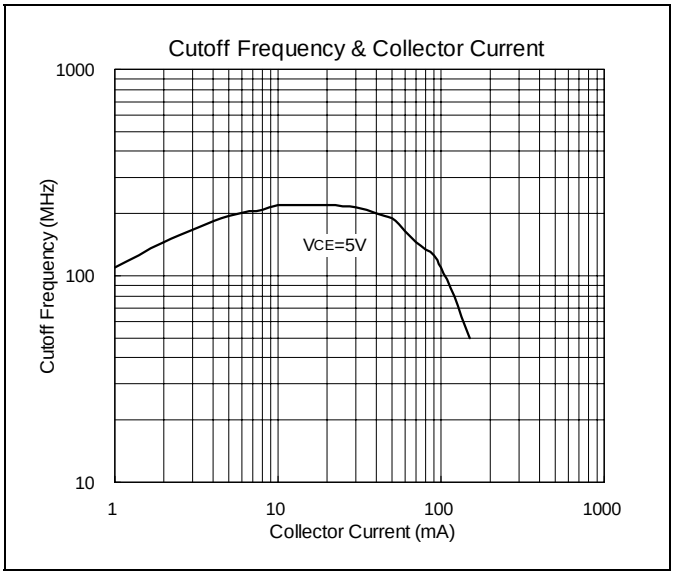
Characteristics Curve

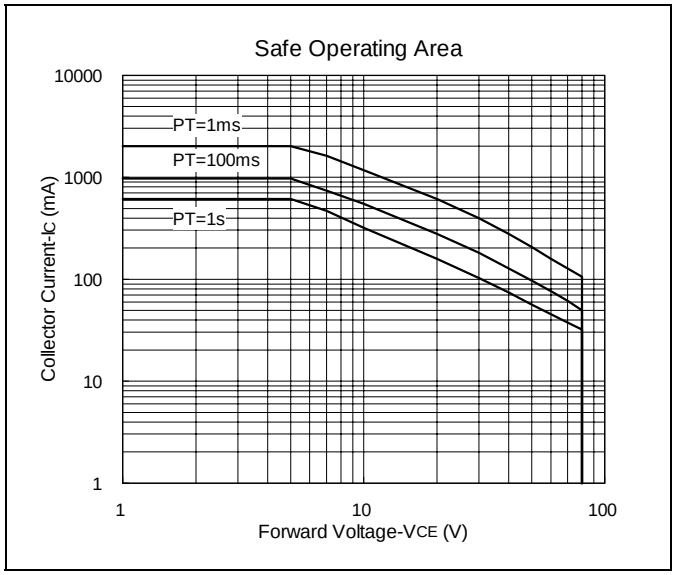




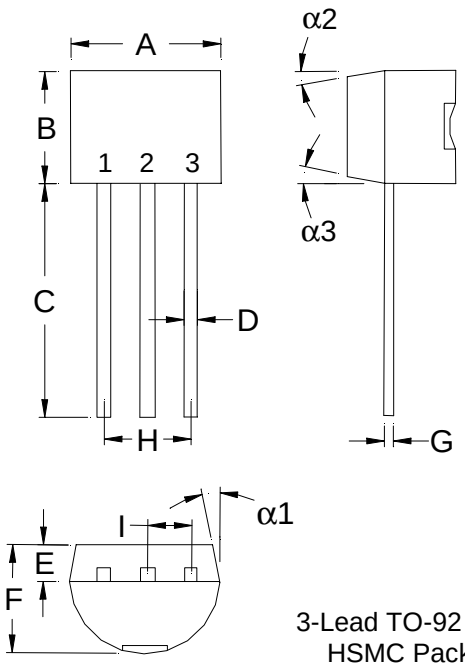






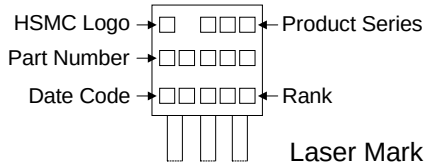


TO-92 Dimension

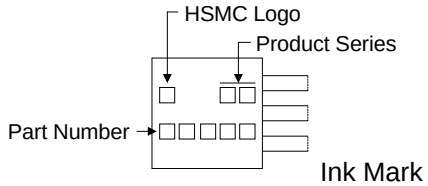


3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :



Laser Mark



Ink Mark

Style : Pin 1.Collector 2.Base 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Head Office And Factory :

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- **Factory 1 :** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel : 886-3-5983621~5 Fax : 886-3-5982931